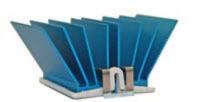
BGA Heat Sink - High Performance maxiFLOW/superGRIP





ATS Part#:

Description:

ATS-X50210B-C1-R0

21.00 x 21.00 x 7.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP

Heat Sink Type:

maxiFLOW Heat Sink Attachment:

Equivalent Part Number: N/A

superGRIP

*Image above is for illustration purpose only.

Features & Benefits

- Designed for 21 x 21 mm components •
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs •
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a • PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB .

Thermal Performance

		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	11.9 °C/W	9.5 °C/W	8.2 °C/W	7.3 °C/W	6.7 °C/W	6.2 °C/W	5.8 °C/W
	Ducted Flow	8.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	21.00 mm	21.00 mm	7.50 mm	34.6 mm	T766	BLUE-ANODIZED
The above is for illustration purpose only.	 Dimension Thermal papplication ATS resense performant ATS certification 	ves the right to upda	eight from the bottor provided for referen ate or change its prov k assembly is RoHS	nce only. Actual perfo ducts without notice -6 and REACH com	ormance to improv	may vary by

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Advanced Thermal Solutions: ATS-X50210B-C1-R0